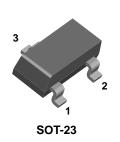
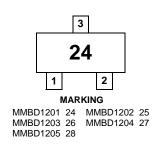
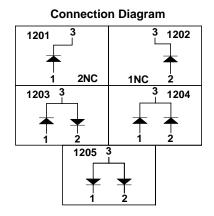


August 2011

MMBD1201 / 1202 / 1203 / 1204 / 1205 Small Signal Diodes







Absolute Maximum Ratings* $T_A = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Units V	
V _{RRM}	Maximum Repetitive Reverse Voltage	100		
I _{F(AV)}	Average Rectified Forward Current	200	mA	
I _{FSM}	Non-repetitive Peak Forward Surge Current			
	Pulse Width = 1.0 second	1.0	Α	
	Pulse Width = 1.0 microsecond	2.0	Α	
T _{STG}	Storage Temperature Range	-55 to +150	°C	
TJ	Operating Junction Temperature	150	°C	

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Value	Units
P _D	Power Dissipation	350	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

Electrical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V _R	Breakdown Voltage	$I_R = 100 \mu A$	100		V
V _F	Forward Voltage	I _F = 1.0mA	550	600	mV
		I _F = 10mA	660	740	mV
		$I_F = 100 \text{mA}$	820	920	mV
		$I_F = 200 \text{mA}$	0.87	1.0	V
		$I_F = 300 \text{mA}$	-	1.1	V
I _R	Reverse Leakage	V _R = 20V		25	nA
		$V_R = 50V$		50	nA
		$V_R = 50V, T_A = 150^{\circ}C$		5.0	μΑ
C _T	Total Capacitance	$V_R = 0, f = 1.0MHz$		2.0	pF
t _{rr}	Reverse Recovery Time	$I_F = I_R = 10 \text{mA}, I_{RR} = 1.0 \text{mA}$ $R_L = 100 \Omega$		4.0	ns

Typical Performance Characteristics

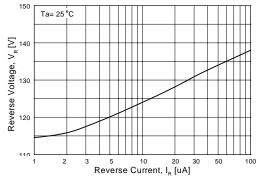


Figure 1. Reverse Voltage vs Reverse Current BV - 1.0 to 100uA

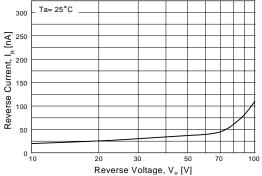


Figure 2. Reverse Current vs Reverse Voltage IR - 10 to 100 V

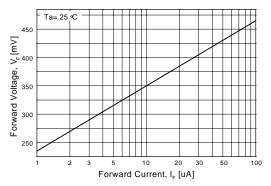


Figure 3. Forward Voltage vs Forward Current VF - 1.0 to 100 uA

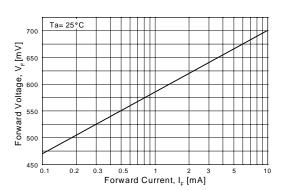


Figure 4. Forward Voltage vs Forward Current VF - 0.1 to 10 mA

Typical Performance Characteristics (Continued)

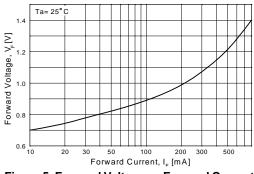


Figure 5. Forward Voltage vs Forward Current VF - 10 - 800 mA

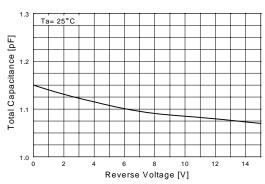


Figure 6. Total Capacitance vs Reverse Voltage

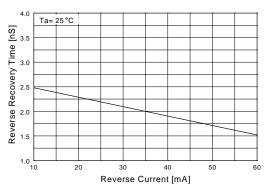


Figure 7. Reverse Recovery Time vs Reverse Current TRR - IR 10 mA vs 60 mA

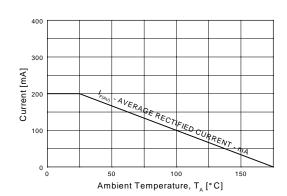


Figure 8. Average Rectified Current $(I_{F(AV)})$ versus Ambient Temperature (T_{Δ})

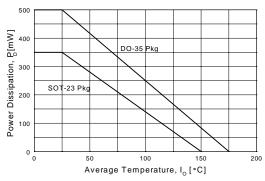


Figure 9. Power Derating Curve





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